

SID

Factory: Rot am See

Article:

569

ML8

Provided:

Landwehr, Melanie

Customer:

Date:

17.12.2015



Processtechnology: B: undefiniert

Material Text	Mat. Nr.	µm	Stackup	Process overview
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A-RS Kupferfolie-035my 330x490mm	50200242	35	VS	1	
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	167		2	
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	0		3	
A-RS-FR4-ML-0.30mm-035+035-TG150-HF	50200655	35	L2	4	A01
		300			
		35	L3		
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	195		5	
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	0		6	
A-RS-FR4-ML-0.30mm-035+035-TG150-HF	50200655	35	L4	7	A02
		300			
		35	L5		
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	195		8	
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	0		9	
A-RS-FR4-ML-0.30mm-035+035-TG150-HF	50200655	35	L6	10	A03
		300			
		35	L7		
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	167		11	
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	0		12	
A-RS Kupferfolie-035my 330x490mm	50200242	35	RS	13	

Thickness after Pressing

B00:

1890 µm

Tol+:

200 µm

Tol-:

200 µm

Dmax:

2090 µm

Dmin:

1690 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

2000 µm

Tol+:

200 µm

Tol-:

200 µm

Dmax:

2200 µm

Dmin:

1800 µm

Measuring point: (05) über LM und galv.Cu; beidseitig

nominal:

1904 µm

Version 1.2.14.15

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